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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	AVR
Core Size	8-Bit
Speed	4MHz
Connectivity	SPI
Peripherals	POR, WDT
Number of I/O	15
Program Memory Size	1KB (512 x 16)
Program Memory Type	FLASH
EEPROM Size	64 x 8
RAM Size	-
Voltage - Supply (Vcc/Vdd)	2.7V ~ 6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at90s1200a-4yc

ing the Registers, Timer/Counter, Watchdog and Interrupt system to continue functioning. The Power-down mode saves the register contents but freezes the Oscillator, disabling all other chip functions until the next External Interrupt or hardware Reset.

The device is manufactured using Atmel's high-density nonvolatile memory technology. The On-chip In-System Programmable Flash allows the program memory to be reprogrammed in-system through an SPI serial interface or by a conventional nonvolatile memory programmer. By combining an enhanced RISC 8-bit CPU with In-System Programmable Flash on a monolithic chip, the Atmel AT90S1200 is a powerful microcontroller that provides a highly flexible and cost-effective solution to many embedded control applications.

The AT90S1200 AVR is supported with a full suite of program and system development tools including: macro assemblers, program debugger/simulators, in-circuit emulators, and evaluation kits.

Pin Descriptions

VCC Supply voltage pin.

GND Ground pin.

Port B (PB7..PB0) Port B is an 8-bit bi-directional I/O port. Port pins can provide internal pull-up resistors (selected for each bit). PB0 and PB1 also serve as the positive input (AIN0) and the negative input (AIN1), respectively, of the On-chip Analog Comparator. The Port B output buffers can sink 20 mA and thus drive LED displays directly. When pins PB0 to PB7 are used as inputs and are externally pulled low, they will source current if the internal pull-up resistors are activated. The Port B pins are tri-stated when a reset condition becomes active, even if the clock is not active.

Port B also serves the functions of various special features of the AT90S1200 as listed on page 30.

Port D (PD6..PD0) Port D has seven bi-directional I/O pins with internal pull-up resistors, PD6..PD0. The Port D output buffers can sink 20 mA. As inputs, Port D pins that are externally pulled low will source current if the pull-up resistors are activated. The Port D pins are tri-stated when a reset condition becomes active, even if the clock is not active.

Port D also serves the functions of various special features of the AT90S1200 as listed on page 34.

$\overline{\text{RESET}}$ Reset input. A low level on this pin for more than 50 ns will generate a reset, even if the clock is not running. Shorter pulses are not guaranteed to generate a reset.

XTAL1 Input to the inverting oscillator amplifier and input to the internal clock operating circuit.

XTAL2 Output from the inverting oscillator amplifier.

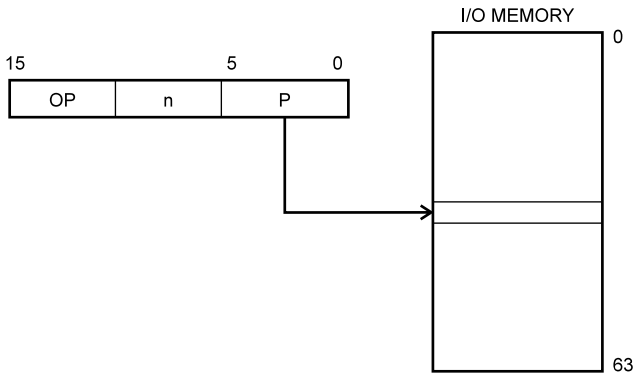
Crystal Oscillator

XTAL1 and XTAL2 are input and output, respectively, of an inverting amplifier which can be configured for use as an On-chip Oscillator, as shown in Figure 2. Either a quartz crystal or a ceramic resonator may be used. To drive the device from an external clock source, XTAL2 should be left unconnected while XTAL1 is driven as shown in Figure 3.

Operands are contained in register r (Rr) and d (Rd). The result is stored in register d (Rd).

I/O Direct

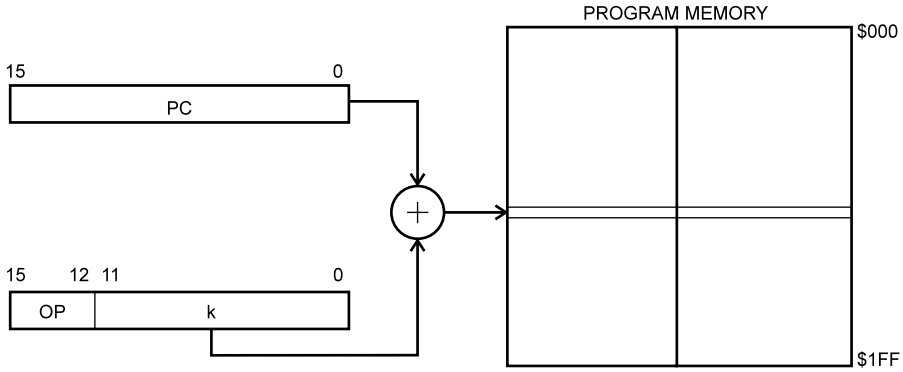
Figure 9. I/O Direct Addressing



Operand address is contained in 6 bits of the instruction word. n is the destination or source register address.

Relative Program Addressing, RJMP and RCALL

Figure 10. Relative Program Memory Addressing



Program execution continues at address PC + k + 1. The relative address k is -2048 to 2047.

Subroutine and Interrupt Hardware Stack

The AT90S1200 uses a 3 level deep hardware stack for subroutines and interrupts. The hardware stack is 9 bits wide and stores the Program Counter (PC) return address while subroutines and interrupts are executed.

RCALL instructions and interrupts push the PC return address onto stack level 0, and the data in the other stack levels 1 - 2 are pushed one level deeper in the stack. When a RET or RETI instruction is executed the returning PC is fetched from stack level 0, and the data in the other stack levels 1 - 2 are popped one level in the stack.

If more than three subsequent subroutine calls or interrupts are executed, the first values written to the stack are overwritten.

EEPROM Data Memory

The AT90S1200 contains 64 bytes of data EEPROM memory. It is organized as a separate data space, in which single bytes can be read and written. The EEPROM has an endurance of at least 100,000 write/erase cycles. The access between the EEPROM and the CPU is described on page 25 specifying the EEPROM address register, the EEPROM data register, and the EEPROM control register. For the SPI data downloading, see page 44 for a detailed description.

Instruction Execution Timing

This section describes the general access timing concepts for instruction execution and internal memory access.

The AVR CPU is driven by the System Clock Ø, directly generated from the external clock crystal for the chip. No internal clock division is used.

Figure 11 shows the parallel instruction fetches and instruction executions enabled by the Harvard architecture and the fast-access register file concept. This is the basic pipelining concept to obtain up to 1 MIPS per MHz with the corresponding unique results for functions per cost, functions per clocks, and functions per power-unit.

Figure 11. The Parallel Instruction Fetches and Instruction Executions

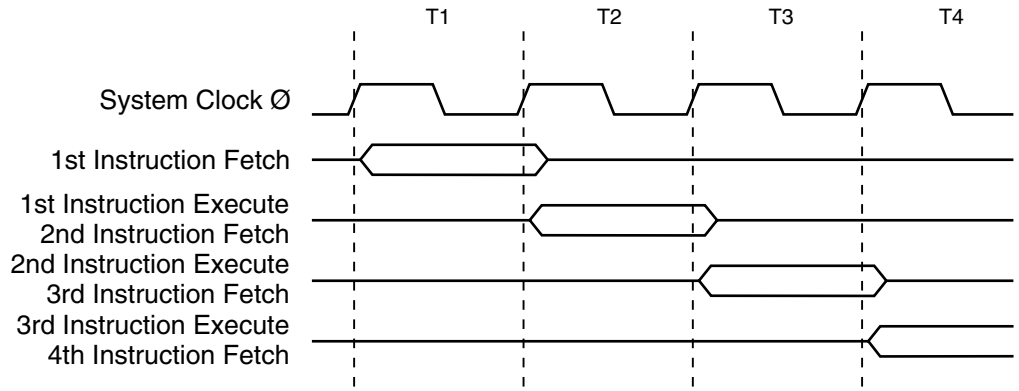
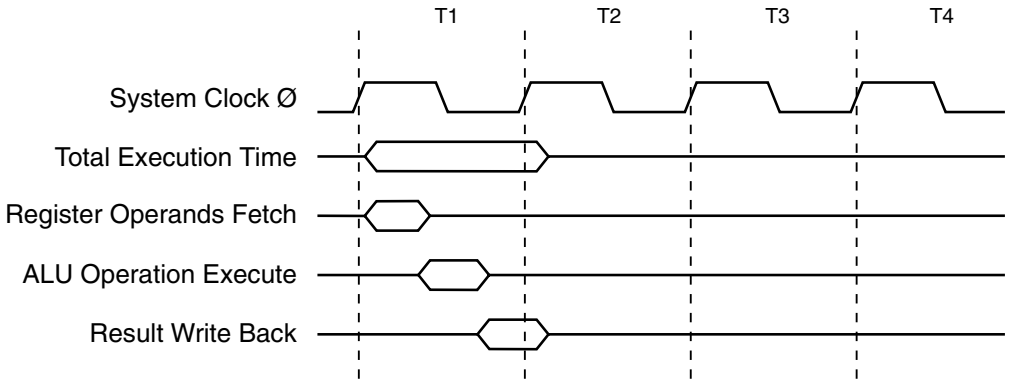


Figure 12 shows the internal timing concept for the register file. In a single clock cycle an ALU operation using two register operands is executed, and the result is stored back to the destination register.

Figure 12. Single-cycle ALU Operation



I/O Memory

The I/O space definition of the AT90S1200 is shown in the following table.

Table 1. The AT90S1200 I/O Space

Address Hex	Name	Function
$3F	SREG	Status REGister
$3B	GIMSK	General Interrupt MaSK register
$39	TIMSK	Timer/Counter Interrupt MaSK register
$38	TIFR	Timer/Counter Interrupt Flag register
$35	MCUCR	MCU general Control Register
$33	TCCR0	Timer/Counter0 Control Register
$32	TCNT0	Timer/Counter0 (8-bit)
$21	WDTCR	Watchdog Timer Control Register
$1E	EEAR	EEPROM Address Register
$1D	EEDR	EEPROM Data Register
$1C	EECR	EEPROM Control Register
$18	PORTB	Data Register, Port B
$17	DDRB	Data Direction Register, Port B
$16	PINB	Input Pins, Port B
$12	PORTD	Data Register, Port D
$11	DDRD	Data Direction Register, Port D
$10	PIND	Input Pins, Port D
$08	ACSR	Analog Comparator Control and Status Register

Note: Reserved and unused locations are not shown in the table.

All AT90S1200 I/Os and peripherals are placed in the I/O space. The different I/O locations are accessed by the IN and OUT instructions transferring data between the 32 general purpose working registers and the I/O space. I/O registers within the address range $00 - $1F are directly bit-accessible using the SBI and CBI instructions. In these registers, the value of single bits can be checked by using the SBIS and SBIC instructions. Refer to the instruction set chapter for more details.

For compatibility with future devices, reserved bits should be written to zero if accessed. Reserved I/O memory addresses should never be written.

Some of the status flags are cleared by writing a logical one to them. Note that the CBI and SBI instructions will operate on all bits in the I/O register, writing a one back into any flag read as set, thus clearing the flag. The CBI and SBI instructions work with registers $00 to $1F only.

The different I/O and peripherals control registers are explained in the following sections.

External Interrupts

The External Interrupt is triggered by the INT0 pin. The interrupt can trigger on rising edge, falling edge or low level. This is set up as described in the specification for the MCU Control Register (MCUCR). When INT0 is level triggered, the interrupt is pending as long as INT0 is held low.

The interrupt is triggered even if INT0 is configured as an output. This provides a way to generate a software interrupt.

The interrupt flag can not be directly accessed by the user. If an external edge-triggered interrupt is suspected to be pending, the flag can be cleared as follows.

1. Disable the External Interrupt by clearing the INT0 flag in GIMSK.
2. Select level triggered interrupt.
3. Select desired interrupt edge.
4. Re-enable the external interrupt by setting INT0 in GIMSK.

Interrupt Response Time

The interrupt execution response for all the enabled AVR interrupts is four clock cycles minimum. Four clock cycles after the interrupt flag has been set, the program vector address for the actual interrupt handling routine is executed. During this 4-clock-cycle period, the Program Counter (9 bits) is pushed onto the Stack. The vector is normally a relative jump to the interrupt routine, and this jump takes two clock cycles. If an interrupt occurs during execution of a multi-cycle instruction, this instruction is completed before the interrupt is served.

A return from an interrupt handling routine takes four clock cycles. During these four clock cycles, the Program Counter (9 bits) is popped back from the Stack and the I-flag in SREG is set. When the AVR exits from an interrupt, it will always return to the main program and execute one more instruction before any pending interrupt is served.

Note that the Subroutine and Interrupt Stack is a 3-level true hardware stack, and if more than three nested subroutines and interrupts are executed, only the most recent three return addresses are stored.

MCU Control Register – MCUCR

The MCU Control Register contains general microcontroller control bits for general MCU control functions.

Bit	7	6	5	4	3	2	1	0	
$35	–	–	SE	SM	–	–	ISC01	ISC00	MCUCR
Read/Write	R	R	R/W	R/W	R	R	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7, 6 – Res: Reserved Bits**

These bits are reserved bits in the AT90S1200 and always read as zero.

- **Bit 5 – SE: Sleep Enable**

The SE bit must be set (one) to make the MCU enter the Sleep mode when the SLEEP instruction is executed. To avoid the MCU entering the Sleep mode unless it is the programmers purpose, it is recommended to set the Sleep Enable SE bit just before the execution of the SLEEP instruction.

- **Bit 4 – SM: Sleep Mode**

This bit selects between the two available sleep modes. When SM is cleared (zero), Idle mode is selected as sleep mode. When SM is set (one), Power-down mode is selected as sleep mode. For details, refer to the paragraph “Sleep Modes” on the following page.

- **Bits 3, 2 – Res: Reserved Bits**

These bits are reserved bits in the AT90S1200 and always read as zero.

- **Bits 1, 0 – ISC01, ISC00: Interrupt Sense Control 0 Bit 1 and Bit 0**

The External Interrupt 0 is activated by the external pin INT0 if the SREG I-flag and the corresponding interrupt mask in the GIMSK register is set. The level and edges on the external INT0 pin that activate the interrupt are defined in Table 4.

Table 4. Interrupt 0 Sense Control

ISC01	ISC00	Description
0	0	The low level of INT0 generates an interrupt request.
0	1	Reserved
1	0	The falling edge of INT0 generates an interrupt request.
1	1	The rising edge of INT0 generates an interrupt request.

The value on the INT0 pin is sampled before detecting edges. If edge interrupt is selected, pulses with a duration longer than one CPU clock period will generate an interrupt. Shorter pulses are not guaranteed to generate an interrupt. If low level interrupt is selected, the low level must be held until the completion of the currently executing instruction to generate an interrupt. If enabled, a level triggered interrupt will generate an interrupt request as long as the pin is held low.

Sleep Modes

To enter the sleep modes, the SE bit in MCUCR must be set (one) and a SLEEP instruction must be executed. If an enabled interrupt occurs while the MCU is in a sleep mode, the MCU awakes, executes the interrupt routine, and resumes execution from the instruction following SLEEP. The contents of the register file and the I/O memory are unaltered. If a Reset occurs during sleep mode, the MCU wakes up and executes from the Reset Vector.

Idle Mode

When the SM bit is cleared (zero), the SLEEP instruction makes the MCU enter the Idle mode, stopping the CPU but allowing Timer/Counters, Watchdog and the interrupt system to continue operating. This enables the MCU to wake up from external triggered interrupts as well as internal ones like Timer Overflow interrupt and Watchdog Reset. If wakeup from the Analog Comparator interrupt is not required, the Analog Comparator can be powered down by setting the ACD-bit in the Analog Comparator Control and Status Register (ACSR). This will reduce power consumption in Idle mode. When the MCU wakes up from Idle mode, the CPU starts program execution immediately.

Power-down Mode

When the SM bit is set (one), the SLEEP instruction makes the MCU enter Power-down mode. In this mode, the External Oscillator is stopped while the External Interrupts and the Watchdog (if enabled) continue operating. Only an External Reset, a Watchdog Reset (if enabled), an external level interrupt on INT0 can wake up the MCU.

Note that when a level triggered interrupt is used for wake-up from Power-down, the low level must be held for a time longer than the reset delay time-out period t_{TOUT}. Otherwise, the device will not wake up.

- **Bits 2, 1, 0 – CS02, CS01, CS00: Clock Select0, Bits 2, 1 and 0**

The Clock Select0 bits 2, 1 and 0 define the prescaling source of Timer/Counter0.

Table 5. Clock 0 Prescale Select

CS02	CS01	CS00	Description
0	0	0	Stop, the Timer/Counter0 is stopped.
0	0	1	CK
0	1	0	CK/8
0	1	1	CK/64
1	0	0	CK/256
1	0	1	CK/1024
1	1	0	External Pin T0, falling edge
1	1	1	External Pin T0, rising edge

The Stop condition provides a Timer Enable/Disable function. The CK down divided modes are scaled directly from the CK Oscillator clock. If the external pin modes are used for Timer/Counter0, transitions on PD4/(T0) will clock the counter even if the pin is configured as an output. This feature can give the user SW control of the counting.

Timer/Counter0 – TCNT0

Bit	7	6	5	4	3	2	1	0	
$32	MSB							LSB	TCNT0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

The Timer/Counter0 is realized as an up-counter with read and write access. If the Timer/Counter0 is written and a clock source is present, the Timer/Counter0 continues counting in the timer clock cycle following the write operation.

Table 6. Watchdog Timer Prescale Select

WDP2	WDP1	WDP0	Number of WDT Oscillator Cycles	Typical Time-out at V_{CC} = 3.0V	Typical Time-out at V_{CC} = 5.0V
0	0	0	16K cycles	47 ms	15 ms
0	0	1	32K cycles	94 ms	30 ms
0	1	0	64K cycles	0.19 s	60 ms
0	1	1	128K cycles	0.38 s	0.12 s
1	0	0	256K cycles	0.75 s	0,24 s
1	0	1	512K cycles	1.5 s	0.49 s
1	1	0	1,024K cycles	3.0 s	0.97 s
1	1	1	2,048K cycles	6.0 s	1.9 s

Note: The frequency of the Watchdog Oscillator is voltage dependent as shown in “Typical Characteristics” on page 51.

The WDR (Watchdog Reset) instruction should always be executed before the Watchdog Timer is enabled. This ensures that the reset period will be in accordance with the Watchdog Timer prescale settings. If the Watchdog Timer is enabled without Reset, the Watchdog Timer may not start to count from zero.

To avoid unintentional MCU resets, the Watchdog Timer should be disabled or reset before changing the Watchdog Timer Prescale Select.

EEPROM Read/Write Access

The EEPROM access registers are accessible in the I/O space.

The write access time is in the range of 2.5 - 4 ms, depending on the V_{CC} voltages. A self-timing function, however, lets the user software detect when the next byte can be written. If the user code contains code that writes the EEPROM, some precaution must be taken. In heavily filtered power supplies, V_{CC} is likely to rise or fall slowly on Power-up/down. This causes the device for some period of time to run at a voltage lower than specified as minimum for the clock frequency used. CPU operation under these conditions is likely cause the program counter to perform unintentional jumps and eventually execute the EEPROM write code. To secure EEPROM integrity, the user is advised to use an external under-voltage reset circuit in this case.

In order to prevent unintentional EEPROM writes, a specific write procedure must be followed. Refer to “EEPROM Control Register – EECR” on page 25 for details on this.

When the EEPROM is read or written, the CPU is halted for two clock cycles before the next instruction is executed.

EEPROM Address Register – EEAR

Bit	7	6	5	4	3	2	1	0	
$1E	–	–	EEAR5	EEAR4	EEAR3	EEAR2	EEAR1	EEAR0	EEAR
Read/Write	R	R	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7, 6 – Res: Reserved Bits**

These bits are reserved bits in the AT90S1200 and will always read as zero.

- **Bits 5..0 – EEAR5..0: EEPROM Address**

The EEPROM Address Register (EEAR5..0) specifies the EEPROM address in the 64-byte EEPROM space. The EEPROM data bytes are addressed linearly between 0 and 63.

EEPROM Data Register – EEDR

Bit	7	6	5	4	3	2	1	0	
$1D	MSB							LSB	EEDR
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7..0 – EEDR7..0: EEPROM Data**

For the EEPROM write operation, the EEDR register contains the data to be written to the EEPROM in the address given by the EEAR register. For the EEPROM read operation, the EEDR contains the data read out from the EEPROM at the address given by EEAR.

EEPROM Control Register – EECR

Bit	7	6	5	4	3	2	1	0	
$1C	–	–	–	–	–	–	EEWE	EERE	EECR
Read/Write	R	R	R	R	R	R	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7..2 – Res: Reserved Bits**

These bits are reserved bits in the AT90S1200 and will always be read as zero.

Figure 25. Port B Schematic Diagram (Pin PB6)

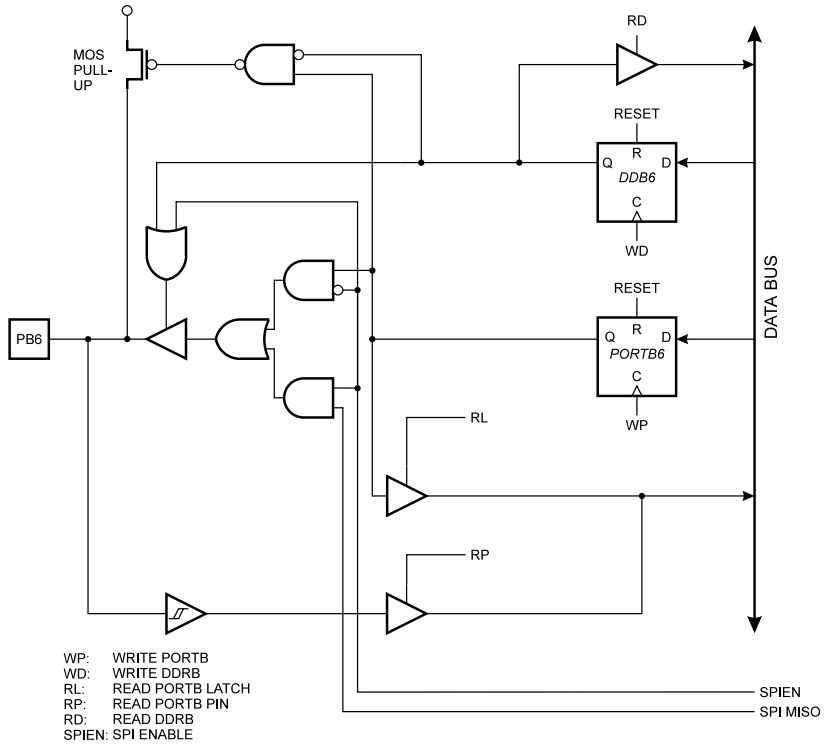
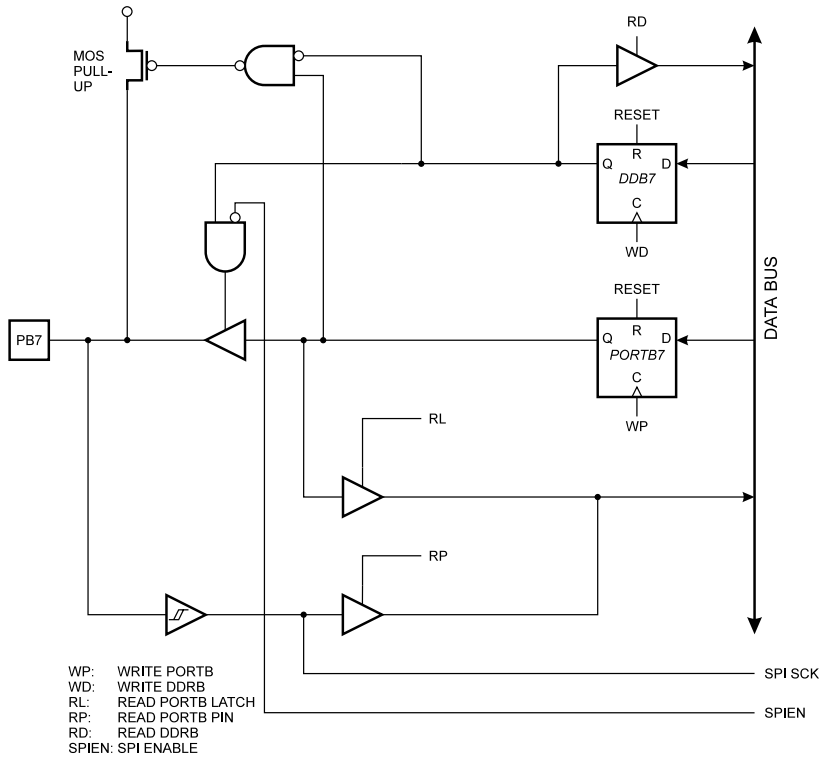


Figure 26. Port B Schematic Diagram (Pin PB7)



4. Give XTAL1 a positive pulse. This loads the command.

B: Load Address High Byte

1. Set XA1, XA0 to “00”. This enables address loading.
2. Set BS to “1”. This selects high byte.
3. Set DATA = Address high byte ($00 - $01).
4. Give XTAL1 a positive pulse. This loads the address high byte.

C: Load Address Low Byte

1. Set XA1, XA0 to “00”. This enables address loading.
2. Set BS to “0”. This selects low byte.
3. Set DATA = Address low byte ($00 - $FF).
4. Give XTAL1 a positive pulse. This loads the address low byte.

D: Load Data Low Byte

1. Set XA1, XA0 to “01”. This enables data loading.
2. Set DATA = Data low byte ($00 - $FF).
3. Give XTAL1 a positive pulse. This loads the data low byte.

E: Write Data Low Byte

1. Set BS to “0”. This selects low data.
2. Give $\overline{WR}$ a negative pulse. This starts programming of the data byte. RDY/$\overline{BSY}$ goes low.
3. Wait until RDY/$\overline{BSY}$ goes high to program the next byte.

(See Figure 31 for signal waveforms.)

F: Load Data High Byte

1. Set XA1, XA0 to “01”. This enables data loading.
2. Set DATA = Data high byte ($00 - $FF).
3. Give XTAL1 a positive pulse. This loads the data high byte.

G: Write Data High Byte

1. Set BS to “1”. This selects high data.
2. Give $\overline{WR}$ a negative pulse. This starts programming of the data byte. RDY/$\overline{BSY}$ goes low.
3. Wait until RDY/$\overline{BSY}$ goes high to program the next byte.

(See Figure 32 for signal waveforms.)

The loaded command and address are retained in the device during programming. For efficient programming, the following should be considered:

- The command needs only be loaded once when writing or reading multiple memory locations.
- Address high byte needs only be loaded before programming a new 256-word page in the Flash.
- Skip writing the data value $FF; that is, the contents of the entire Flash and EEPROM after a Chip Erase.

These considerations also apply to EEPROM programming and Flash, EEPROM and signature byte reading.

Figure 31. Programming the Flash Waveforms

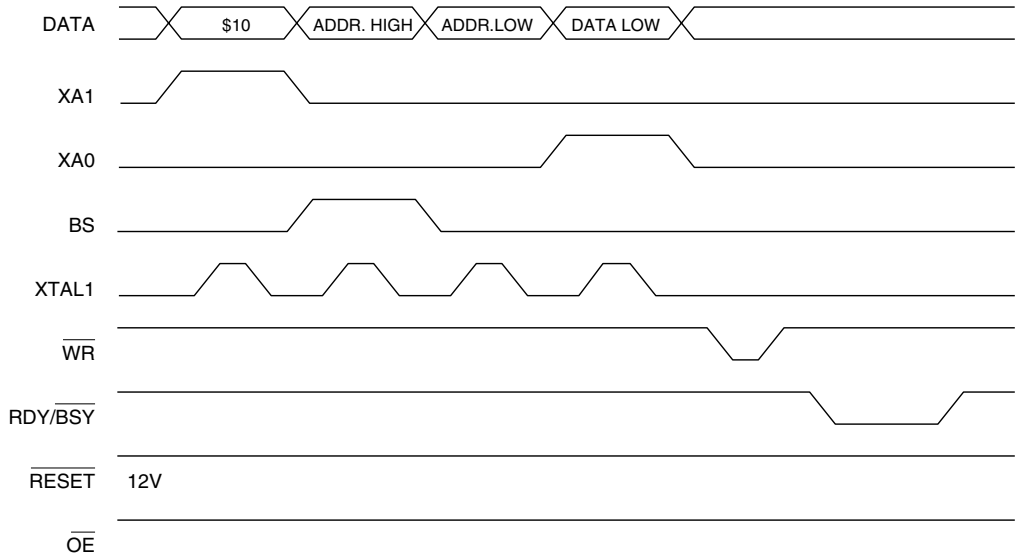
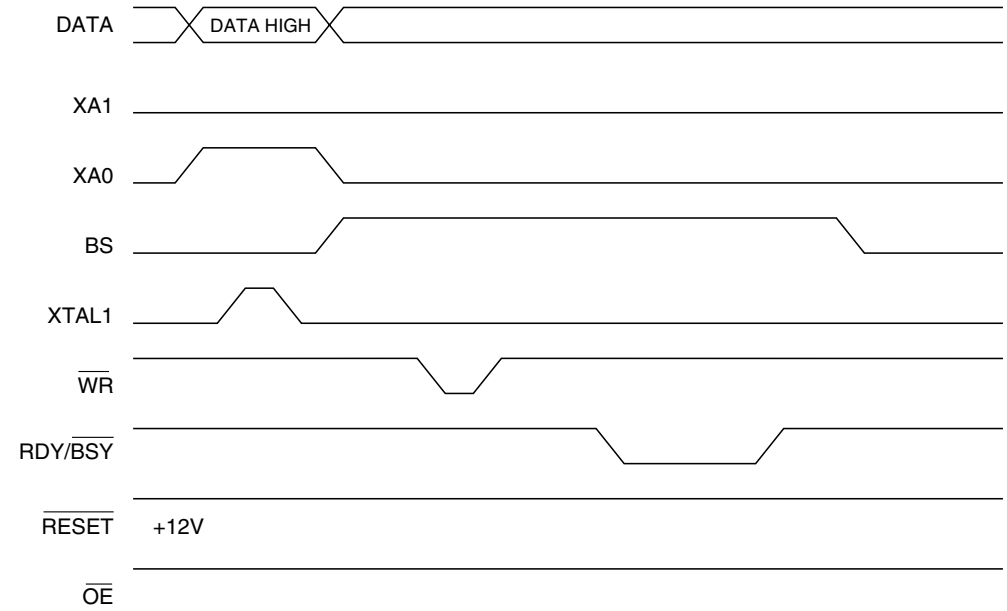


Figure 32. Programming the Flash Waveforms (Continued)



Reading the Flash

The algorithm for reading the Flash memory is as follows (refer to “Programming the Flash” for details on command and address loading):

1. A: Load Command “0000 0010”.
2. B: Load Address High Byte ($00 - $01).
3. C: Load Address Low Byte ($00 - $FF).
4. Set $\overline{OE}$ to “0”, and BS to “0”. The Flash word low byte can now be read at DATA.
5. Set BS to “1”. The Flash word high byte can now be read from DATA.
6. Set $\overline{OE}$ to “1”.

Reading the Signature Bytes

The algorithm for reading the signature bytes is as follows (refer to "Programming the Flash" on page 39 for details on command and address loading):

1. A: Load Command "0000 1000".
2. C: Load Address Low Byte ($00 - $02).
   Set $\overline{OE}$ to "0", and BS to "0". The selected signature byte can now be read at DATA.
   Set $\overline{OE}$ to "1".

Parallel Programming Characteristics

Figure 33. Parallel Programming Timing

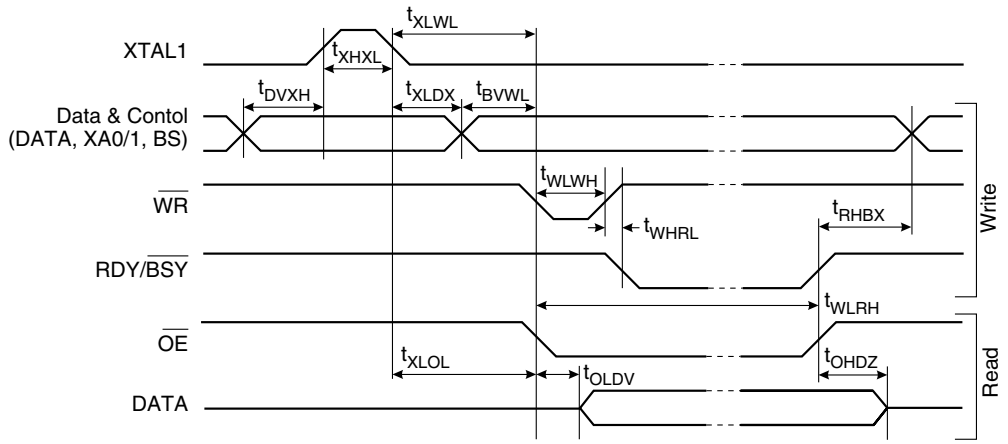


Table 17. Parallel Programming Characteristics, T_A = 25°C ± 10%, V_{CC} = 5V ± 10%

Symbol	Parameter	Min	Typ	Max	Units
V_{PP}	Programming Enable Voltage	11.5		12.5	V
I_{PP}	Programming Enable Current			250.0	µA
t_{DVXH}	Data and Control Setup before XTAL1 High	67.0			ns
t_{XHXL}	XTAL1 Pulse Width High	67.0			ns
t_{XLDX}	Data and Control Hold after XTAL1 Low	67.0			ns
t_{XLWL}	XTAL1 Low to $\overline{WR}$ Low	67.0			ns
t_{BVWL}	BS Valid to $\overline{WR}$ Low	67.0			ns
t_{RHBX}	BS Hold after RDY/$\overline{BSY}$ High	67.0			ns
t_{WLWH}	$\overline{WR}$ Pulse Width Low(1)	67.0			ns
t_{WHRL}	$\overline{WR}$ High to RDY/$\overline{BSY}$ Low(2)		20.0		ns
t_{WLRH}	$\overline{WR}$ Low to RDY/$\overline{BSY}$ High(2)	0.5	0.7	0.9	ms
t_{XLOL}	XTAL1 Low to $\overline{OE}$ Low	67.0			ns
t_{OLDV}	$\overline{OE}$ Low to DATA Valid		20.0		ns
t_{OHDZ}	$\overline{OE}$ High to DATA Tri-stated			20.0	ns
t_{WLWH_CE}	$\overline{WR}$ Pulse Width Low for Chip Erase	5.0	10.0	15.0	ms
t_{WLWH_PFB}	$\overline{WR}$ Pulse Width Low for Programming the Fuse Bits	1.0	1.5	1.8	ms

Notes: 1. Use t_{WLWH_CE} for chip erase and t_{WLWH_PFB} for programming the Fuse bits.
2. If t_{WLWH} is held longer than t_{WLRH}, no RDY/$\overline{BSY}$ pulse will be seen.

Electrical Characteristics

Absolute Maximum Ratings*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on Any Pin Except $\overline{\text{RESET}}$ with Respect to Ground	-1.0V to V_{CC}+0.5V
Voltage on $\overline{\text{RESET}}$ with Respect to Ground	-1.0V to +13.0V
Maximum Operating Voltage	6.6V
DC Current per I/O Pin	40.0 mA
DC Current V_{CC} and GND Pins	200.0 mA

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC Characteristics

T_A = -40×C to 85×C, V_{CC} = 2.7V to 6.0V (unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{IL}	Input Low Voltage	(Except XTAL1)	-0.5		0.3 V_{CC}(1)	V
V_{IL1}	Input Low Voltage	(XTAL1)	-0.5		0.3 V_{CC}(1)	V
V_{IH}	Input High Voltage	(Except XTAL1, $\overline{\text{RESET}}$)	0.6 V_{CC}(2)		V_{CC} + 0.5	V
V_{IH1}	Input High Voltage	(XTAL1)	0.7 V_{CC}(2)		V_{CC} + 0.5	V
V_{IH2}	Input High Voltage	($\overline{\text{RESET}}$)	0.85 V_{CC}(2)		V_{CC} + 0.5	V
V_{OL}	Output Low Voltage(3) (Ports B, D)	I_{OL} = 20 mA, V_{CC} = 5V I_{OL} = 10 mA, V_{CC} = 3V			0.6 0.5	V V
V_{OH}	Output High Voltage(4) (Ports B, D)	I_{OH} = -3 mA, V_{CC} = 5V I_{OH} = -1.5 mA, V_{CC} = 3V	4.3 2.3			V V
I_{IL}	Input Leakage Current I/O pin	V_{CC} = 6V, pin low (absolute value)			8.0	µA
I_{IH}	Input Leakage Current I/O pin	V_{CC} = 6V, pin high (absolute value)			980.0	nA
RRST	Reset Pull-up Resistor		100.0		500.0	kΩ
$R_{I/O}$	I/O Pin Pull-up Resistor		35.0		120.0	kΩ
I_{CC}	Power Supply Current	Active Mode, V_{CC} = 3V, 4 MHz			3.0	mA
		Idle Mode V_{CC} = 3V, 4 MHz			1.0	mA
I_{CC}	Power-down mode(5)	WDT enabled, V_{CC} = 3V		9.0	15.0	µA
		WDT disabled, V_{CC} = 3V		<1.0	2.0	µA

DC Characteristics

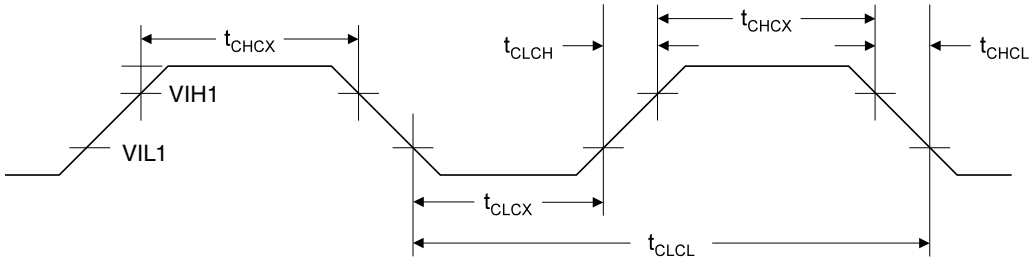
T_A = -40×C to 85×C, V_{CC} = 2.7V to 6.0V (unless otherwise noted) (Continued)

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{ACIO}	Analog Comparator Input Offset Voltage	V_{CC} = 5V V_{in} = V_{CC}/ 2			40.0	mV
I_{ACLK}	Analog Comparator Input Leakage Current	V_{CC} = 5V V_{in} = V_{CC}/ 2	-50.0		50.0	nA
t_{ACPD}	Analog Comparator Propagation Delay	V_{CC} = 2.7V V_{CC} = 4.0V		750.0 500.0		ns

Notes:
1. “Max” means the highest value where the pin is guaranteed to be read as low.
2. “Min” means the lowest value where the pin is guaranteed to be read as high.
3. Although each I/O port can sink more than the test conditions (20 mA at V_{CC} = 5V, 10 mA at V_{CC} = 3V) under steady state conditions (non-transient), the following must be observed:
   1] The sum of all I_{OL}, for all ports, should not exceed 200 mA.
   2] The sum of all I_{OL}, for port D0 - D5 and XTAL2, should not exceed 100 mA.
   3] The sum of all I_{OL}, for ports B0 - B7 and D6, should not exceed 100 mA.
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test condition.
4. Although each I/O port can source more than the test conditions (3 mA at V_{CC} = 5V, 1.5 mA at V_{CC} = 3V) under steady state conditions (non-transient), the following must be observed:
   1] The sum of all I_{OH}, for all ports, should not exceed 200 mA.
   2] The sum of all I_{OH}, for port D0 - D5 and XTAL2, should not exceed 100 mA.
   3] The sum of all I_{OH}, for ports B0 - B7 and D6, should not exceed 100 mA.
   If I_{OH} exceeds the test condition, V_{OH} may exceed the related specification. Pins are not guaranteed to source current greater than the listed test condition.
5. Minimum V_{CC} for power-down is 2V.

External Clock Drive Waveforms

Figure 37. External Clock Drive



External Clock Drive

Table 23. External Clock Drive

Symbol	Parameter	V_{CC} = 2.7V to 4.0V		V_{CC} = 4.0V to 6.0V		Units
		Min	Max	Min	Max	
$1/t_{CLCL}$	Oscillator Frequency	0	4.0	0	12.0	MHz
t_{CLCL}	Clock Period	250.0		83.3		ns
t_{CHCX}	High Time	100.0		33.3		ns
t_{CLCX}	Low Time	100.0		33.3		ns
t_{CLCH}	Rise Time		1.6		0.5	µs
t_{CHCL}	Fall Time		1.6		0.5	µs

Typical Characteristics

The following charts show typical behavior. These figures are not tested during manufacturing. All current consumption measurements are performed with all I/O pins configured as inputs and with internal pull-ups enabled. A sine wave generator with rail-to-rail output is used as clock source.

The power consumption in Power-down mode is independent of clock selection.

The current consumption is a function of several factors such as: operating voltage, operating frequency, loading of I/O pins, switching rate of I/O pins, code executed and ambient temperature. The dominating factors are operating voltage and frequency.

The current drawn from capacitive loaded pins may be estimated (for one pin) as $C_L \bullet V_{CC} \bullet f$ where C_L = load capacitance, V_{CC} = operating voltage and f = average switching frequency of I/O pin.

The parts are characterized at frequencies higher than test limits. Parts are not guaranteed to function properly at frequencies higher than the ordering code indicates.

The difference between current consumption in Power-down mode with Watchdog Timer enabled and Power-down mode with Watchdog Timer disabled represents the differential current drawn by the Watchdog Timer.

Figure 38. Active Supply Current vs. Frequency

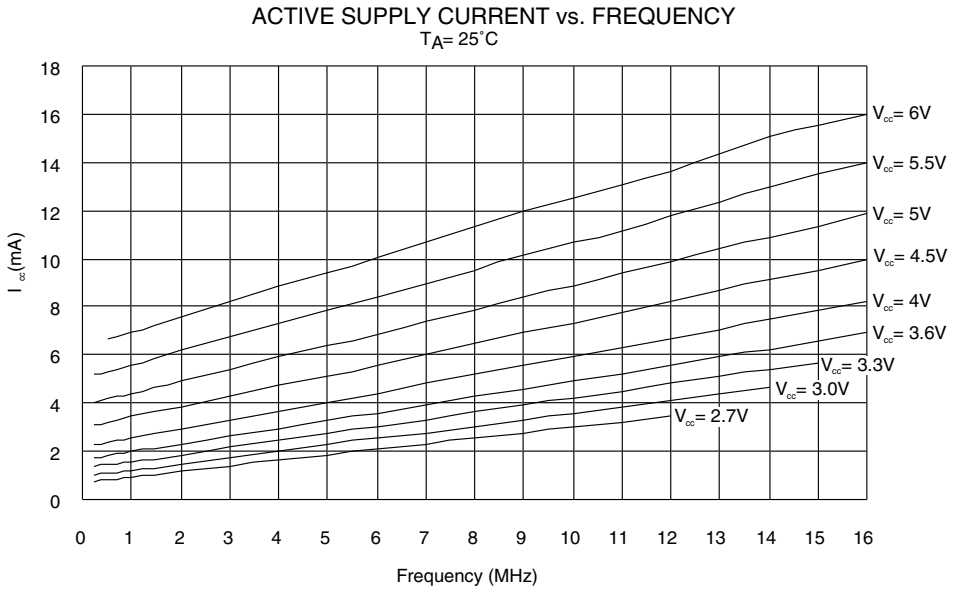


Figure 39. Active Supply Current vs. V_{CC}

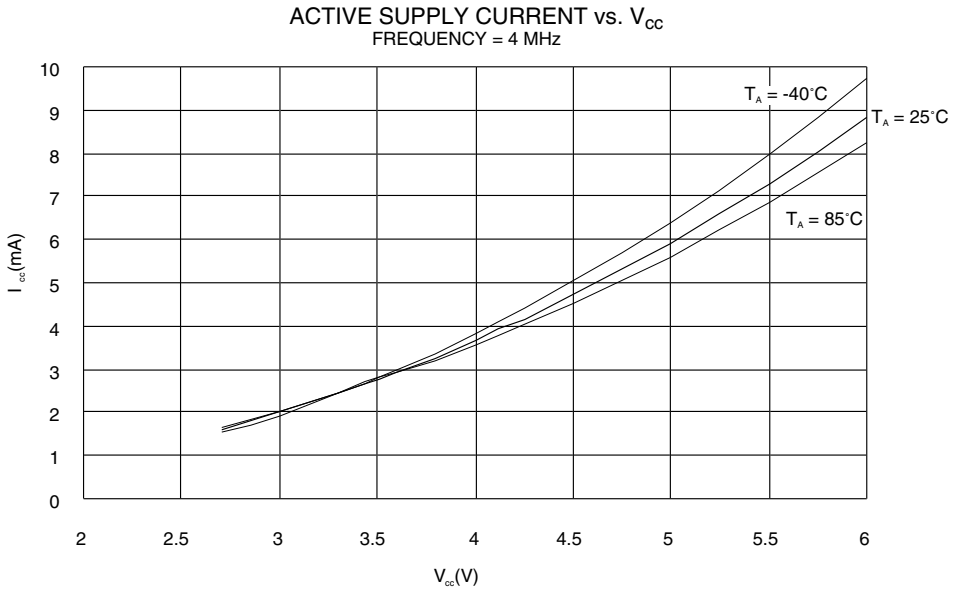
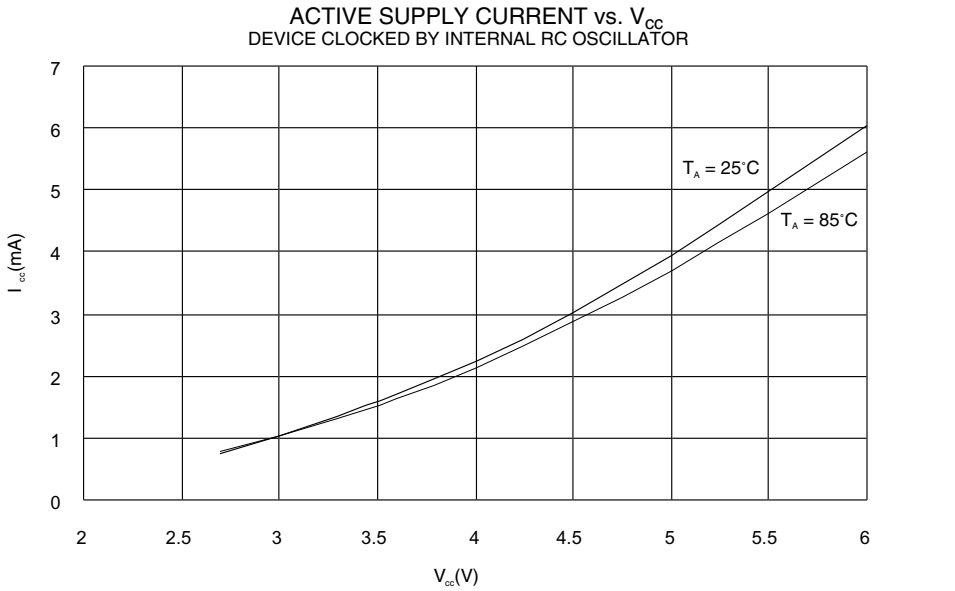


Figure 40. Active Supply Current vs. V_{CC}, Device Clocked by Internal Oscillator



Atmel Headquarters

Corporate Headquarters
2325 Orchard Parkway
San Jose, CA 95131
TEL 1(408) 441-0311
FAX 1(408) 487-2600

Europe
Atmel SarL
Route des Arsenaux 41
Casa Postale 80
CH-1705 Fribourg
Switzerland
TEL (41) 26-426-5555
FAX (41) 26-426-5500

Asia
Atmel Asia, Ltd.
Room 1219
Chinachem Golden Plaza
77 Mody Road Tsimhatsui
East Kowloon
Hong Kong
TEL (852) 2721-9778
FAX (852) 2722-1369

Japan
Atmel Japan K.K.
9F, Tonetsu Shinkawa Bldg.
1-24-8 Shinkawa
Chuo-ku, Tokyo 104-0033
Japan
TEL (81) 3-3523-3551
FAX (81) 3-3523-7581

Atmel Operations

Memory
Atmel Corporate
2325 Orchard Parkway
San Jose, CA 95131
TEL 1(408) 436-4270
FAX 1(408) 436-4314

Microcontrollers
Atmel Corporate
2325 Orchard Parkway
San Jose, CA 95131
TEL 1(408) 436-4270
FAX 1(408) 436-4314

Atmel Nantes
La Chantrerie
BP 70602
44306 Nantes Cedex 3, France
TEL (33) 2-40-18-18-18
FAX (33) 2-40-18-19-60

ASIC/ASSP/Smart Cards
Atmel Rousset
Zone Industrielle
13106 Rousset Cedex, France
TEL (33) 4-42-53-60-00
FAX (33) 4-42-53-60-01

Atmel Colorado Springs
1150 East Cheyenne Mtn. Blvd.
Colorado Springs, CO 80906
TEL 1(719) 576-3300
FAX 1(719) 540-1759

Atmel Smart Card ICs
Scottish Enterprise Technology Park
Maxwell Building
East Kilbride G75 0QR, Scotland
TEL (44) 1355-803-000
FAX (44) 1355-242-743

RF/Automotive
Atmel Heilbronn
Theresienstrasse 2
Postfach 3535
74025 Heilbronn, Germany
TEL (49) 71-31-67-0
FAX (49) 71-31-67-2340

Atmel Colorado Springs
1150 East Cheyenne Mtn. Blvd.
Colorado Springs, CO 80906
TEL 1(719) 576-3300
FAX 1(719) 540-1759

Biometrics/Imaging/Hi-Rel MPU/
High Speed Converters/RF Datacom
Atmel Grenoble
Avenue de Rochepleine
BP 123
38521 Saint-Egreve Cedex, France
TEL (33) 4-76-58-30-00
FAX (33) 4-76-58-34-80

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e-mail
literature@atmel.com

Web Site
http://www.atmel.com

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